

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3906	substrate and ground and (via through adj hole) and die and bond\$4 and (pad contact) and wire adj bond\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/05 13:27
L2	56	(substrate and ground and (via through adj hole) and die and bond\$4 and (pad contact) and wire adj bond\$4).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/05 13:30
L3	34	(substrate and ground and (via through adj hole) and die and bond\$4 and (pad contact) and (line stripline microstrip conductor trace) and wire adj bond\$4).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/05 13:35
L4	3724	(substrate and ground and (via through adj hole) and die and bond\$4 and (pad contact) and (line stripline microstrip conductor trace) and wire adj bond\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/05 13:36
L5	93	(substrate same ground same (via through adj hole) same die same bond\$4 same (pad contact) same (line stripline microstrip conductor trace) same wire adj bond\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/05 13:36
L6	76	5 not (2 3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/05 13:43
L7	4005	((333/246) or (333/247) or (333/33) or (333/238) or (333/260)).CCLS	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/05 13:43
L8	68	7 and @pd>="20050713"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/05 13:44